

*Cont'd
B1*

etching a via (14,15,16) in the dielectric layer (13) over the conductor (3,4,5), and
stopping on the etch stop layer (12) to create an exposed part of the etch stop layer (12);
removing the exposed part of the etch stop layer (12) inside the via (14,15,16)
from at least the top surface portion (6) of the conductor (3,4,5); and
filling the via (14,15,16) with a conductive material (18).
